
Description

The CXA2765ER is a laser driver IC that can drive optical disk lasers capable of writing the three formats of CD, DVD and BD.

(Applications: Writable 3-wavelength optical disk drive)

Features

- ◆ Supports power save mode with register setting LDOFF
- ◆ LD drivers
 - ◆ Three LD drivers for CD, DVD and BD
 - ◆ Maximum driving current
 - OUTBD: Total = 450mA (Each channel: 150mA, 200mA, 150mA, 50mA, 150mA)
 - OUT1, OUT2: Total = 800mA (Each channel: 180mA, 400mA, 300mA, 150mA, 180mA)
 - ◆ Driver current noise: $0.4\text{nA}/\sqrt{\text{Hz}}$ (Read)
 - ◆ 5-channel control allows generation of a 5-value recording waveform
 - ◆ Register setting of high-frequency modulator (HFM) frequency and amplitude
 - Frequency: 200MHz to 600MHz, 8 bits
 - Amplitude: 0mAp-p to 100mAp-p, 8 bits
 - ◆ IOP monitor using the VIOPMON pin (BD only)
 - ◆ VOP monitor using the VIOPMON pin
 - ◆ Register setting of HFM spectrum diffusion function (Modulation frequency: 2 bits, diffusion frequency: 2 bits)

Package

32-pin VQFN (Plastic)

Structure

CMOS IC

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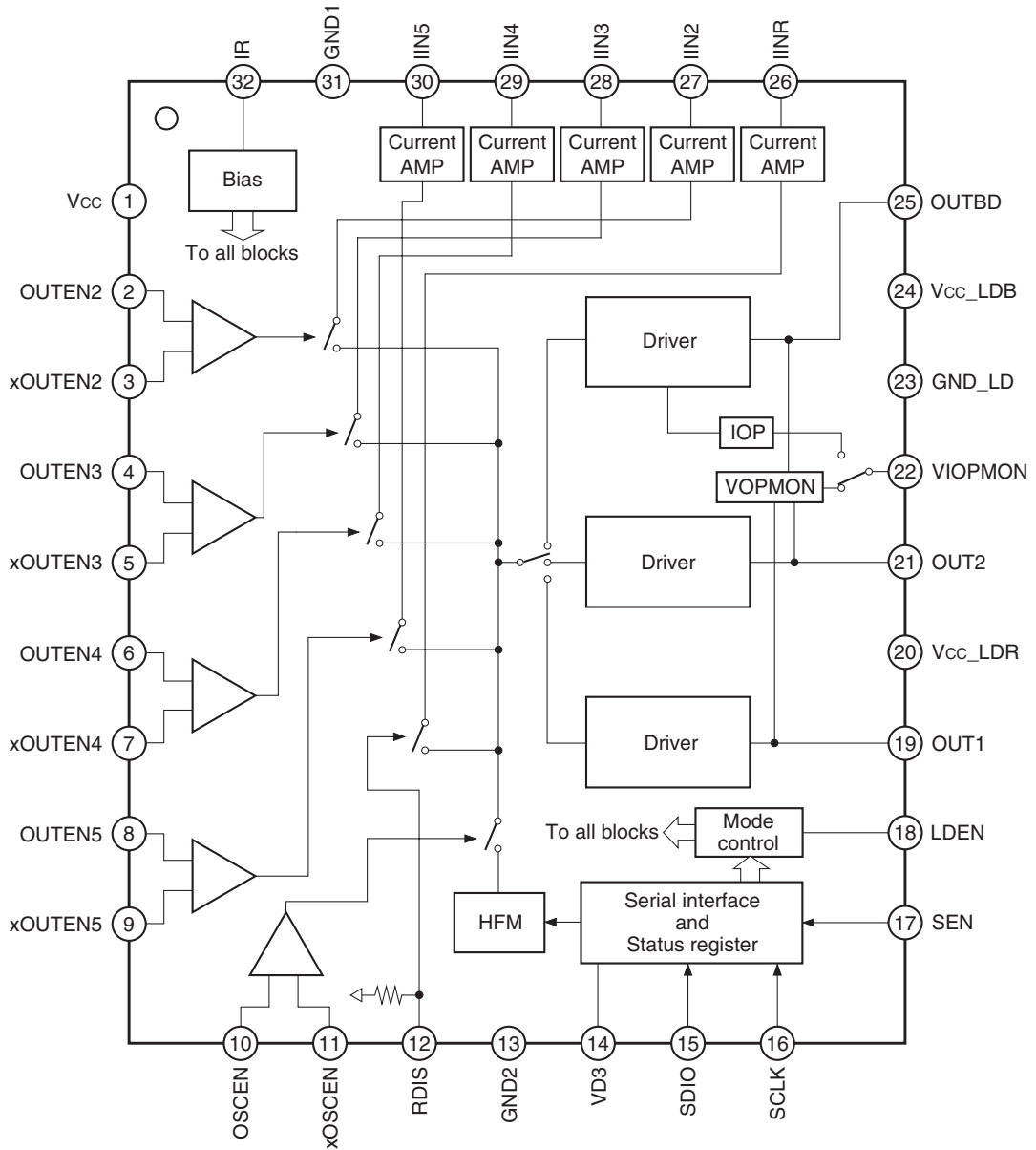
Absolute Maximum Ratings

♦ Supply voltage	V _{CC}	6	V
	V _{CC_LDR}	6	V
	V _{CC_LDB}	10.0	V (When BD_LD is OFF)
♦ Storage temperature	T _{stg}	-65 to +150	°C
♦ Junction temperature	T _{jmax}	150	°C
♦ OUTBD pin voltage	OUTBD_OFF	< 7	V (When BD_LD is OFF)

Operating Conditions

♦ Supply voltage	V _{CC}	4.5 to 6	V
	V _{CC_LDR}	4.5 to 6	V
	V _{CC_LDB}	5 to 9	V (When BD_LD is ON)
♦ Operating temperature	T _{opr}	$-10 \leq T_{opr} \leq 150 - \Delta T_j$	°C
♦ OUTBD pin voltage	OUTBD_ON	< 5	V (When BD_LD is ON)

Block Diagram and Pin Configuration



Pin Description

Pin No.	Symbol	I/O	Pin voltage [V]	Equivalent circuit	Description
1	Vcc	—	4.5 to 6.0	—	Supply voltage for input signal, bias and timing blocks
2	OUTEN2	I	—		IIN2 setting current control signal input (positive logic): LVDS/CMOS Fix to GND when not used.
3	xOUTEN2	I	—		IIN2 setting current control signal input (negative logic): LVDS Not used in single input mode. Fix to Vcc when not used.
4	OUTEN3	I	—		IIN3 setting current control signal input (positive logic): LVDS/CMOS Fix to GND when not used.
5	xOUTEN3	I	—		IIN3 setting current control signal input (negative logic): LVDS Not used in single input mode. Fix to Vcc when not used.
6	OUTEN4	I	—		IIN4 setting current control signal input (positive logic): LVDS/CMOS Fix to GND when not used.
7	xOUTEN4	I	—		IIN4 setting current control signal input (negative logic): LVDS Not used in single input mode. Fix to Vcc when not used.
8	OUTEN5	I	—		IIN5 setting current control signal input (positive logic): LVDS/CMOS Fix to GND when not used.
9	xOUTEN5	I	—		IIN5 setting current control signal input (negative logic): LVDS Not used in single input mode. Fix to Vcc when not used.
10	OSCEN	I	—		HFM control signal input (positive logic): LVDS Not used in single input mode. Fix to GND when not used.
11	xOSCEN	I	—		HFM control signal input (negative logic): LVDS/CMOS Fix to Vcc when not used.
12	RDIS	I	—		

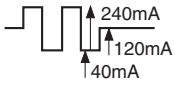
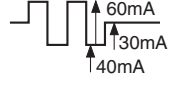
Pin No.	Symbol	I/O	Pin voltage [V]	Equivalent circuit	Description
13	GND2	—	—	—	Timing block GND
14	VD3	—	3.3		Voltage decoupling for serial register circuit (Connect to GND through 0.1μF.)
15	SDIO	I/O	—		Serial register data I/O
16	SCLK	I	—		Serial register clock input (with pull-down resistor)
17	SEN	I	—		Serial register chip select input (with pull-down resistor)
18	LDEN	I	—		LDEN control (with pull-down resistor) High: LD enabled Low: Power save

Pin No.	Symbol	I/O	Pin voltage [V]	Equivalent circuit	Description
19	OUT1	O	—		Laser driving output 1
20	Vcc_LDR	—	4.5 to 6.0		Supply voltage for output stage
21	OUT2	O	—		Laser driving output 2
22	VIOPMON	O	—		Monitor output
23	GND_LD	—	—		Output stage GND
24	Vcc_LDB	—	5 to 9		Supply voltage for blue-violet LD
25	OUTBD	O	—		Laser driving output (for BD)
26	IINR	I	—		Current setting R

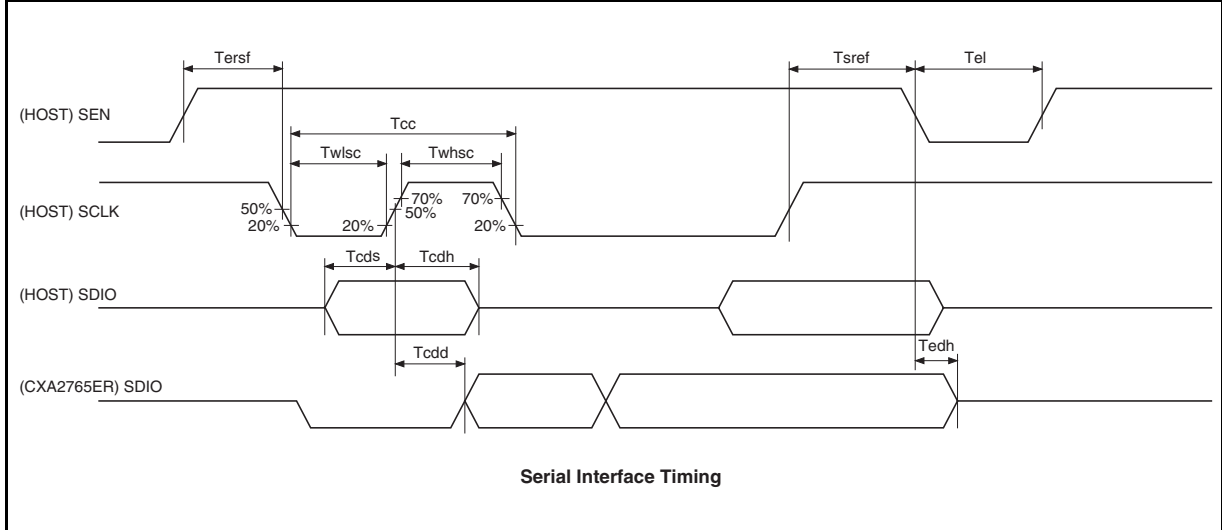
Pin No.	Symbol	I/O	Pin voltage [V]	Equivalent circuit	Description
27	IIN2	I	—		Current setting 2
28	IIN3	I	—		Current setting 3
29	IIN4	I	—		Current setting 4
30	IIN5	I	—		Current setting 5
31	GND1	—	—	—	Input signal block and bias block GND
32	IR	—	1.25		Reference current setting resistor connection (Connect to GND through 22kΩ.)

Electrical Characteristics

(Vcc = Vcc_LDR = 5V, Vcc_LDB = 8V, Ta = 25°C)

TEST No.	Item	Symbol	Min.	Typ.	Max.	Unit	Conditions
<Current Consumption>							
1	Current consumption 1 (LDOFF)	Icc1	1.2	2.1	3.0	mA	LDEN = Low or LDM = 00
2	Current consumption 2 (CD, DVD_STANDBY)	Icc2	5	12	19	mA	LDEN = High and LDM = 01 or 02 IINR, 2, 3, 4, 5 = 0 RDIS = OSCEN = OUTEN2, 3, 4, 5 = Disable
3	Current consumption 3 (CD, DVD_Read)	Icc3	21	31	41	mA	RDIS, OSCEN = Enable OUT1 or OUT2 = 40mA, modulation amplitude = 20mAp-p Current consumption excluding the OUT1 and OUT2 pin current.
4	Current consumption 4 (CD, DVD_Write)	Icc4	26	38	50	mA	RDIS, OUTEN2, OUTEN3 = Enable (IOUTr, IOU2, IOU3) IOUTr = 40mA (Duty = 100%) IOU2 = 240mA (Duty = 25%) IOU3 = 120mA (Duty = 50%) Current consumption excluding the OUT1 and OUT2 pin current. 
5	Current consumption 5 (BD_STANDBY)	Icc5	7	10	13	mA	LDEN = High and LDM = 03 IINR, 2, 3, 4, 5 = 0 RDIS = OSCEN = OUTEN2, 3, 4, 5 = Disable
6	Current consumption 6 (BD_Read)	Icc6	14	20	26	mA	RDIS, OSCEN = Enable OUTBD = 40mA, modulation amplitude = 20mAp-p Current consumption excluding the OUTBD pin current.
7	Current consumption 7 (BD_Write)	Icc7	16	23	30	mA	RDIS, OUTEN2, OUTEN3 = Enable (IOUTr, IOU2, IOU3) IOUTr = 40mA (Duty = 100%) IOU2 = 60mA (Duty = 25%) IOU3 = 30mA (Duty = 50%) Current consumption excluding the OUTBD pin current. 

TEST No.	Item	Symbol	Min.	Typ.	Max.	Unit	Conditions
<Serial Interface AC Characteristics>							
8	SCLK operating range	Fser	—	—	20	MHz	
9	SCLK "H" pulse width	Twhsc	13	—	—	ns	
10	SCLK "L" pulse width	Twlsc	13	—	—	ns	
11	SEN "L" time	Tel	26	—	—	ns	
12	SEN rising edge to the first SCLK falling edge	Tersf	15	—	—	ns	
13	SDIO set up time	Tcds	15	—	—	ns	
14	SDIO hold time	Tcdh	15	—	—	ns	
15	Last SCLK rising edge to SEN falling edge	Tsref	1/Fser	—	—	s	
16	SCLK cycle time ¹	Tcc	50	—	—	ns	
17	SDIO output delay	Tcdd	—	—	15	ns	
18	SDIO output hold time	Tedh	—	5.1	—	ns	



Serial Interface Timing

<CMOS Logic Input>							
19	Input voltage High level	VSH	2.1	—	3.6	V	Pins 2, 4, 6, 8, 11, 12 and 15 to 18
20	Input voltage Low level	VSL	0	—	0.6	V	Pins 2, 4, 6, 8, 11, 12 and 15 to 18
21	Input current 1 (High level)	ISH1	51	72	120	μA	Pins 16 to 18 (VSH = 3.6V)
22	Input current 1 (Low level)	ISL1	-10	—	10	μA	Pins 16 to 18 (VSL = 0V)
23	Input current 2	IS2	-10	—	10	μA	Pins 2, 4, 6, 8, 11
24	Input current 3 (High level)	ISH3	-24	-14	-9	μA	Pin 12 (VSH = 3.6V)
25	Input current 3 (Low level)	ISL3	-84	-50	-35	μA	Pin 12 (VSL = 0V)
<CMOS Logic Output>							
26	Output voltage High level	VOSH	2.8	—	3.3	V	Pin 15 (IOH = 3mA)
27	Output voltage Low level	VOSL	0	—	0.4	V	Pin 15 (IOL = 3mA)
28	VD3 voltage variance	VVD3	3.1	—	3.5	V	Pin 14
<Differential Input>							
29	Input voltage range	VDR	0	—	3	V	Pins 2 to 11
30	Differential input amplitude	VDTH	0.2	—	1	V	Pins 2 to 11
31	Input current	ID	-10	—	10	μA	Pins 2 to 11

TEST No.	Item	Symbol	Min.	Typ.	Max.	Unit	Conditions
<LD Driver DC Characteristics>							
32	Total maximum driving current (CD, DVD)	IMAX	800	—	—	mA	OUT1, 2 = 3.5V
33	IINR CH maximum driving current (CD, DVD)	IMAXR	180	—	—	mA	OUT1, 2 = 3.5V
34	IIN2 CH maximum driving current (CD, DVD)	IMAX2	400	—	—	mA	OUT1, 2 = 3.5V
35	IIN3 CH maximum driving current (CD, DVD)	IMAX3	300	—	—	mA	OUT1, 2 = 3.5V
36	IIN4 CH maximum driving current (CD, DVD)	IMAX4	150	—	—	mA	OUT1, 2 = 3.5V
37	IIN5 CH maximum driving current (CD, DVD)	IMAX5	180	—	—	mA	OUT1, 2 = 3.5V
38	Total minimum driving current (CD, DVD)	IMIN	—	—	10	mA	OUT1, 2 = 3.5V
39	IINR CH minimum driving current (CD, DVD)	IMINR	—	—	4.3	mA	OUT1, 2 = 3.5V
40	IIN2 CH minimum driving current (CD, DVD)	IMIN2	—	—	5.1	mA	OUT1, 2 = 3.5V
41	IIN3 CH minimum driving current (CD, DVD)	IMIN3	—	—	4.0	mA	OUT1, 2 = 3.5V
42	IIN4 CH minimum driving current (CD, DVD)	IMIN4	—	—	1.9	mA	OUT1, 2 = 3.5V
43	IIN5 CH minimum driving current (CD, DVD)	IMIN5	—	—	3.6	mA	OUT1, 2 = 3.5V
44	Total maximum driving current (BD)	IMAX_BD	450	—	—	mA	OUTBD = 1.5V
45	IINR CH maximum driving current (BD)	IMAXR_BD	150	—	—	mA	OUTBD = 1.5V
46	IIN2 CH maximum driving current (BD)	IMAX2_BD	200	—	—	mA	OUTBD = 1.5V
47	IIN3 CH maximum driving current (BD)	IMAX3_BD	150	—	—	mA	OUTBD = 1.5V
48	IIN4 CH maximum driving current (BD)	IMAX4_BD	50	—	—	mA	OUTBD = 1.5V
49	IIN5 CH maximum driving current (BD)	IMAX5_BD	150	—	—	mA	OUTBD = 1.5V
50	Total minimum driving current (BD)	IMIN_BD	-1.1	—	6.0	mA	OUTBD = 1.5V
51	IINR CH minimum driving current (BD)	IMINR_BD	0	—	2.3	mA	OUTBD = 1.5V, measured value – (IOP when RDIS = OUTENx = Disable)
52	IIN2 CH minimum driving current (BD)	IMIN2_BD	0	—	2.7	mA	OUTBD = 1.5V, measured value – (IOP when RDIS = OUTENx = Disable)
53	IIN3 CH minimum driving current (BD)	IMIN3_BD	0	—	2.0	mA	OUTBD = 1.5V, measured value – (IOP when RDIS = OUTENx = Disable)
54	IIN4 CH minimum driving current (BD)	IMIN4_BD	0	—	0.7	mA	OUTBD = 1.5V, measured value – (IOP when RDIS = OUTENx = Disable)
55	IIN5 CH minimum driving current (BD)	IMIN5_BD	0	—	3.0	mA	OUTBD = 1.5V, measured value – (IOP when RDIS = OUTENx = Disable)
56	Read noise 1 (CD, DVD)	RNS1	—	0.31	—	nA/√Hz	OUT1, 2 = 40mA, OSCEN = Disable 16.5MHz noise, HFMP = 32d

TEST No.	Item	Symbol	Min.	Typ.	Max.	Unit	Conditions
57	Read noise 2 (CD, DVD)	RNS2	—	0.42	—	nA/√Hz	OUT1, 2 = 40mA, OSCEN = Enable (20mAp-p, 350MHz) 16.5MHz noise, HFMP = 32d
58	Write noise 1 (CD, DVD)	WNS1	—	2.4	—	nA/√Hz	RDIS, OUTEN2 = Enable IOUTR = 40mA (Duty = 100%) IOUT2 = 40mA (Duty = 50%) 16.5MHz noise
59	Write noise 2 (CD, DVD)	WNS2	—	2.8	—	nA/√Hz	OUTEN5, OUTEN2 = Enable IOUT5 = 40mA (Duty = 100%) IOUT2 = 40mA (Duty = 50%) 16.5MHz noise
60	Read noise 1 (BD)	RNS1_BD	—	0.46	—	nA/√Hz	OUTBD = 40mA, OSCEN = Disable 16.5MHz noise, HFMP = 79d
61	Read noise 2 (BD)	RNS2_BD	—	0.47	—	nA/√Hz	OUTBD = 40mA, OSCEN = Enable (20mAp-p, 350MHz) 16.5MHz noise, HFMP = 79d
62	Write noise 1 (BD)	WNS1_BD	—	1.8	—	nA/√Hz	RDIS, OUTEN2 = Enable IOUTR = 40mA (Duty = 100%) IOUT2 = 40mA (Duty = 50%) 16.5MHz noise
63	Write noise 2 (BD)	WNS2_BD	—	2.4	—	nA/√Hz	OUTEN5, OUTEN2 = Enable IOUT5 = 40mA (Duty = 100%) IOUT2 = 40mA (Duty = 50%) 16.5MHz noise
<LD Driver AC Characteristics>							
64	Rise time (CD, DVD resistance load)	Tr	—	0.5	—	ns	50mA to 100mA pulse, settling 10% to 90% Load = 5Ω//10pF
65	Fall time (CD, DVD resistance load)	Tf	—	0.5	—	ns	
66	Overshoot (CD, DVD resistance load)	OVS+	—	10	—	%	
67	Propagation delay 1 (CD, DVD resistance load)	DELAY1	—	5.6	—	ns	OUT1/2 output ON response time from OUTEN2/3/4/5 differential input
68	Propagation delay 2 (CD, DVD resistance load)	DELAY2	—	5.3	—	ns	OUT1/2 output OFF response time from OUTEN2/3/4/5 differential input
69	Rise time (BD resistance load)	Tr_BD	—	0.5	—	ns	50mA to 100mA pulse, settling 10% to 90% Load = 10Ω//10pF
70	Fall time (BD resistance load)	Tf_BD	—	0.5	—	ns	
71	Overshoot (BD resistance load)	OVS+_BD	—	10	—	%	
72	Propagation delay 1 (BD resistance load)	DELAY1_BD	—	4.6	—	ns	OUTBD output ON response time from OUTEN2/3/4/5 differential input
73	Propagation delay 2 (BD resistance load)	DELAY2_BD	—	4	—	ns	OUTBD output OFF response time from OUTEN2/3/4/5 differential input

TEST No.	Item	Symbol	Min.	Typ.	Max.	Unit	Conditions
<I/O Characteristics>							
74	Input resistance R, 5	ZINR	518	740	962	Ω	IINR/5 input resistance
75	Input resistance 2, 3, 4	ZINW	700	1000	1300	Ω	IIN2/3/4 input resistance
76	Input current R, 2, 3, 4, 5	IIN	0	—	1	mA	IINR/2/3/4/5 input current
77	I/O band R	FBANDR	—	370	—	kHz	IINR = 200 μ A input
78	I/O band 2, 3, 4, 5	FBANDW	—	2.35	—	MHz	IIN2/3/4/5 = 400 μ A input
79	I/O gain R (CD, DVD)	GAINR	235	262	289	A/A	Gain from IINR input to OUT1/2 output (IINR = 100 μ A to 200 μ A, OUT1/2 = 2.5V)
80	I/O gain 5 (CD, DVD)	GAIN5	235	262	289	A/A	Gain from IIN5 input to OUT1/2 output (IIN5 = 100 μ A to 200 μ A, OUT1/2 = 2.5V)
81	I/O gain 2 (CD, DVD)	GAIN2	504	560	616	A/A	Gain from IIN2 input to OUT1/2 output (IINR = 200 μ A, IIN2 = 100 μ A to 200 μ A, OUT1/2 = 2.5V)
82	I/O gain 3 (CD, DVD)	GAIN3	405	450	495	A/A	Gain from IIN3 input to OUT1/2 output (IINR = 200 μ A, IIN3 = 100 μ A to 200 μ A, OUT1/2 = 2.5V)
83	I/O gain 4 (CD, DVD)	GAIN4	202	225	248	A/A	Gain from IIN4 input to OUT1/2 output (IINR = 200 μ A, IIN4 = 100 μ A to 200 μ A, OUT1/2 = 2.5V)
84	I/O linearity 2, 3, 4 (CD, DVD)	LINE	-3	—	3	%	Fix IINR to 200 μ A, and measure the offset at IIN2/3/4 = 600 μ A in reference to IIN2/3/4 = 100 μ A to 200 μ A, respectively. OUT1/2 = 2.5V
85	I/O gain ratio 1 (CD, DVD)	GaRa1	0.9	1	1.1	—	IIN5/IINR gain ratio
86	I/O gain ratio 2 (CD, DVD)	GaRa2	0.72	0.8	0.88	—	IIN3/IIN2 gain ratio
87	I/O gain ratio 3 (CD, DVD)	GaRa3	0.36	0.4	0.44	—	IIN4/IIN2 gain ratio
88	I/O gain R (BD)	GAINR_BD	180	200	221	A/A	Gain from IINR input to OUTBD output (IINR = 100 μ A to 200 μ A, OUTBD = 2.5V)
89	I/O gain 5 (BD)	GAIN5_BD	180	200	221	A/A	Gain from IIN5 input to OUTBD output (IIN5 = 100 μ A to 200 μ A, OUTBD = 2.5V)
90	I/O gain 2 (BD)	GAIN2_BD	238	265	291	A/A	Gain from IIN2 input to OUTBD output (IINR = 200 μ A, IIN2 = 100 μ A to 200 μ A, OUTBD = 2.5V)
91	I/O gain 3 (BD)	GAIN3_BD	180	200	220	A/A	Gain from IIN3 input to OUTBD output (IINR = 200 μ A, IIN3 = 100 μ A to 200 μ A, OUTBD = 2.5V)
92	I/O gain 4 (BD)	GAIN4_BD	59	66	73	A/A	Gain from IIN4 input to OUTBD output (IINR = 200 μ A, IIN4 = 100 μ A to 200 μ A, OUTBD = 2.5V)
93	I/O linearity 2, 3, 4 (BD)	LINE_BD	-3	—	3	%	Fix IINR to 200 μ A, and measure the offset at IIN2/3/4 = 600 μ A in reference to IIN2/3/4 = 100 μ A to 200 μ A, respectively. OUTBD = 2.5V
94	I/O gain ratio 1 (BD)	GaRa1_BD	0.91	1	1.12	—	IIN5/IINR gain ratio
95	I/O gain ratio 2 (BD)	GaRa2_BD	0.67	0.75	0.83	—	IIN3/IIN2 gain ratio
96	I/O gain ratio 3 (BD)	GaRa3_BD	0.22	0.25	0.28	—	IIN4/IIN2 gain ratio

TEST No.	Item	Symbol	Min.	Typ.	Max.	Unit	Conditions
<High-frequency Modulation (HFM)>							
97	Frequency variable range	VARIF	200	—	600	MHz	HFMF = 0 to 255dec
98	Frequency variance	FREQ	-10	—	10	%	HFMF = 80dec (@350MHz)
99	Frequency temperature coefficient	TFREQ	—	-0.0035	—	%/°C	HFMF = 80dec (@350MHz)
100	Amplitude setting range (CD, DVD)	VARIA	0	—	100	mAp-p	HFMF = 80dec (@350MHz), HFMP = 0 to 255dec Load = 5Ω
101	Amplitude setting range (BD)	VARIA_BD	0	—	70	mAp-p	HFMF = 80dec (@350MHz), HFMP = 31 to 255dec, LDCR2 = 00 Load = 10Ω
102	OSCEN response time – ON	OSCRE S1	—	—	11	ns	OSCEN Disable → Enable
103	OSCEN response time – OFF	OSCRE S2	—	—	11	ns	OSCEN Enable → Disable
<LDOFF>							
104	LDOFF response time	LDOFFRES	—	—	10	ns	Time for the output current to fall to 10% when LDEN is changed from High to Low.
105	Power supply monitor circuit – LDOFF	EMON	3.1	3.5	—	V	V _{cc} and V _{cc_LDR} voltages at which LDOFF results.
106	Power supply monitor circuit – LDON	EMOFF	—	3.75	4.15	V	V _{cc} and V _{cc_LDR} voltages at which LDOFF is canceled.
<VIMON>							
107	VOP monitor upper limit (CD, DVD)	VmoMax	4.90	5	5.05	V	VIMON = 001 VIMON voltage when 5V is applied to OUT1/2.
108	VOP monitor lower limit (CD, DVD)	VmoMin	0	0.7	1.1	V	VIMON = 001 VIMON voltage when 0V is applied to OUT1/2.
109	VOP monitor DC accuracy (CD, DVD)	VmoDC	3.9	4	4.1	V	VIMON = 001 VIMON voltage when 4V is applied to OUT1/2.
110	VOP monitor pulse accuracy (CD, DVD)	VmoPls	3.8	4	4.1	V	VIMON output voltage when a 3V to 4V, duty 50%, 6ns pulse is input to OUT1/2. (Peak hold accuracy)
111	VOP monitor hold capability (CD, DVD)	VmoHd	-72	-53.5	-25	mV/μs	VIMON = 001
112	VOP monitor upper limit (BD)	VmoMax_BD	2.4	2.5	2.6	V	VIMON = 001 VIMON voltage when 5V is applied to OUTBD.
113	VOP monitor lower limit (BD)	VmoMin_BD	0	—	0.15	V	VIMON = 001 VIMON voltage when 0V is applied to OUTBD.
114	VOP monitor DC accuracy (BD)	VmoDC_BD	0.4	0.5	0.6	V	VIMON = 001 VIMON voltage when 1V is applied to OUTBD.
115	VOP monitor pulse accuracy (BD)	VmoPls_BD	0.4	0.5	0.7	V	VIMON output voltage when a 1V to 2V, duty 50%, 6ns pulse is input to OUTBD. (Bottom hold accuracy)
116	VOP monitor hold capability (BD)	VmoHd_BD	23	54	73	mV/μs	VIMON = 001
117	Temperature monitor output voltage	TmoVout	—	1.34	—	V	VIMON = 010, T _j = 70°C
118	Temperature monitor temperature coefficient	Tmotemp	—	3.5	—	mV/°C	VIMON = 010
119	IOP monitor current efficiency (BD only)	Iratio_BD	0.914	1	1.053	%	VIMON = 100, IMON/IOUTBD current ratio when OUTBD = 40mA. VIOPMON = 2V



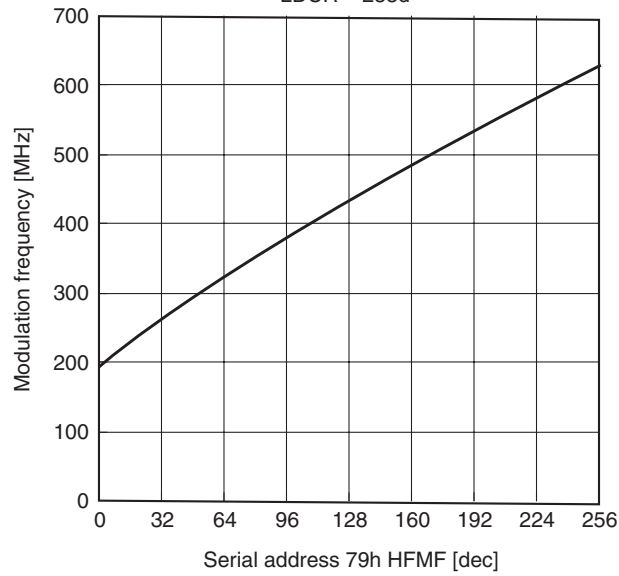
Example of Representative Characteristics

◆ High-frequency Modulation Characteristics

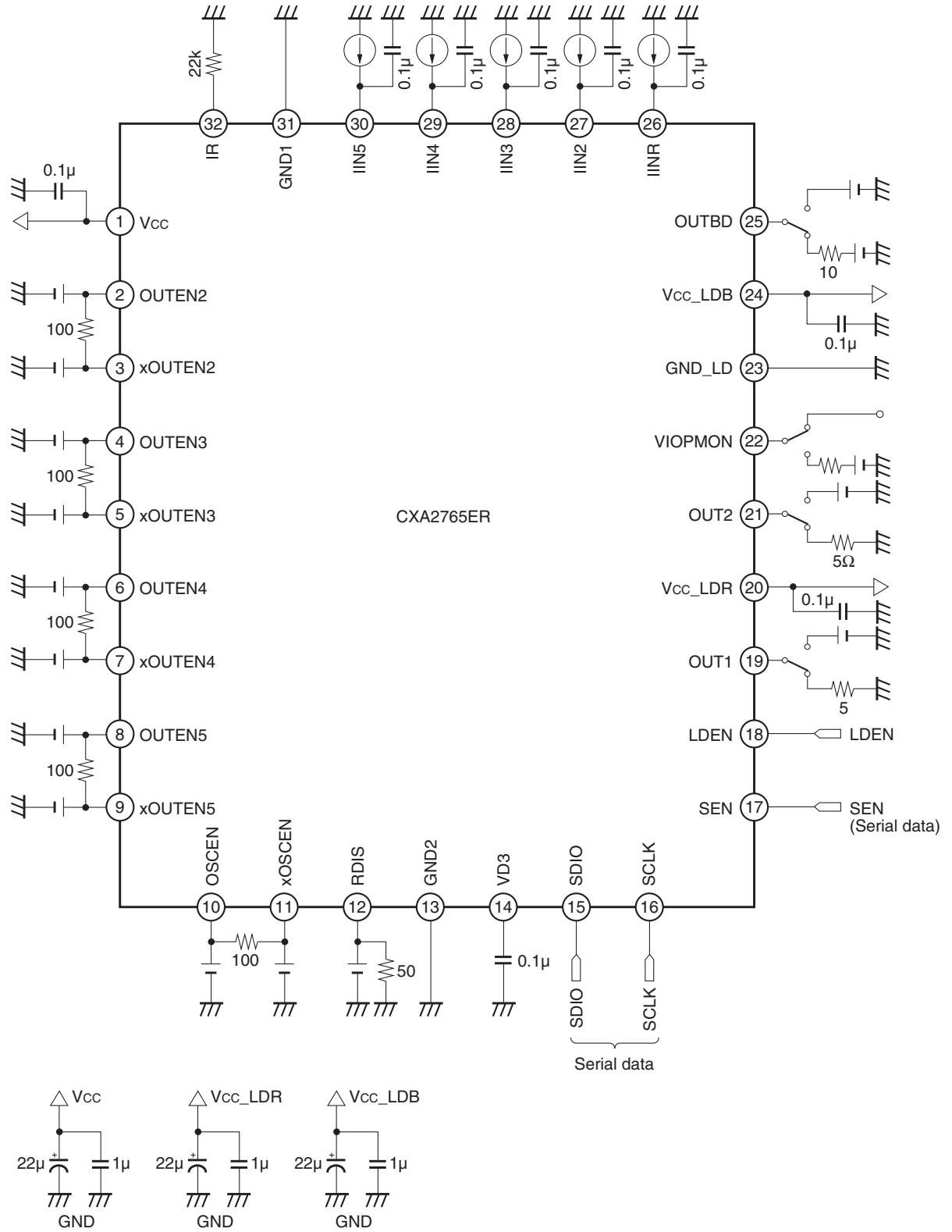
Control characteristics of HFMF and modulation frequency

HFMP = 80d

LDCR = 255d



Electrical Characteristics Measurement Circuit



Serial Interface

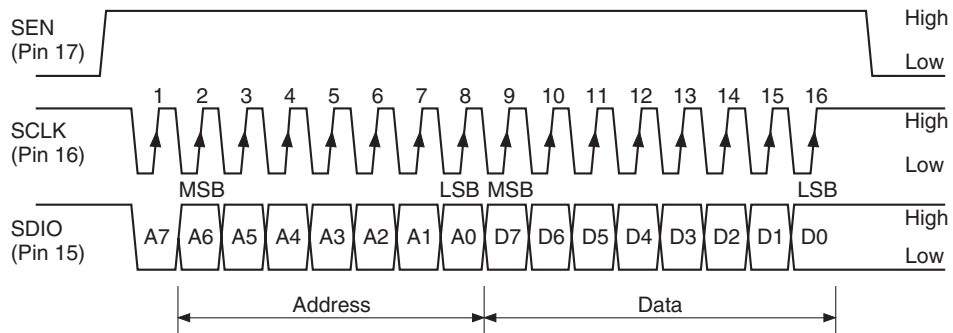
The CXA2765ER performs IC control via the serial interface. The serial interface specifications are shown below.

Serial Address Bit Definition

Bit	Bit definition
A7	Read/write select bit 0: Serial interface write mode 1: Serial interface read mode
A6 to 0	Register address select bit

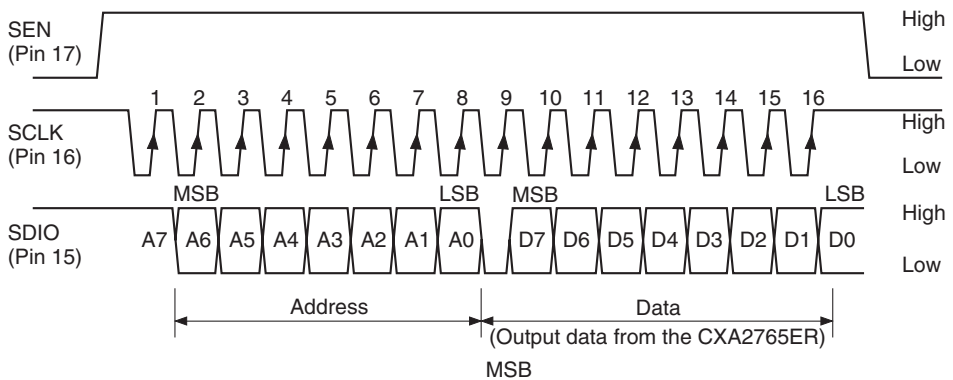
Transmission and reception are performed in 16-bit units consisting of 8 address bits and 8 data bits. Both the address and data are MSB first. In the address, the A[7] bit switches between read and write mode, and the A[6:0] bits are the register address. The read/write timing charts are shown below.

Timing Chart in Write Mode



The data written in the register is reflected to the various IC internal functions at the rising edge of the 16th (last) SCLK signal.

Timing Chart in Read Mode



Note) Depending on the flexible PC board condition, when the SDIO line and the SEN line use adjacent wiring, SDIO signal fluctuations may be transmitted to the SEN line and make the control status unstable, with the result that correct data cannot be read and written during serial transfer.

Address Map

(SDIO/SEN/SCLK)

Address	Name	Definition
78	MODELDD	LDD status (LDOFF/CD/DVD/BD) Transfer skew check, input logic selection, and power supply monitor circuit control
79	HFMP	Modulation amplitude setting (CD/DVD: 0 to 100mAp-p, BD: 0 to 70mAp-p)
7A	HFMF	Modulation frequency setting (200MHz to 600MHz)
7B	EMISEL	HFM spectrum diffusion setting, monitor control
7C	LDCR	Output waveform adjustment
7D	CHSEL	Channel control method selection

Bit Map

Serial Address 78h

Bit	Symbol	Bit definition
7	—	Don't care
6	EMVCCDIS	Power supply monitor circuit disable 0: Enable 1: Disable
5	SEL_CH5	CH5 input logic level selection 0: Differential input 1: Single input
4	SEL_CH2-4	CH2 to CH4 input logic level selection 0: Differential input 1: Single input
3	SEL_OSC	OSC CH input logic level selection 0: Differential input 1: Single input
2	SKEW	Skew check function 0: Normal operation 1: Transfer skew check mode
1-0	LDM	LDD output selection 00: LDOFF (Power save) 01: LD1 10: LD2 11: BD

Serial Address 79h

Bit	Symbol	Bit definition	
		HFM amplitude setting	
		CD/DVD	BD
7-0	HFMP	Resolution = 0.4mAp-p 0d: 0mAp-p to 128d: 50mAp-p to 255d: 100mAp-p	Resolution = 0.3mAp-p 31d: 0mAp-p to 128d: 30mAp-p to 255d: 70mAp-p

Serial Address 7Ah

Bit	Symbol	Bit definition
7-0	HFMF	HFM frequency setting 0d: 200MHz to 255d: 600MHz

Serial Address 7Bh

Bit	Symbol	Bit definition
7-5	VIMON	V/I monitor output selection 000: OFF (monitor circuit power save) 001: VOP monitor output in accordance with LDM 010: Temperature sensor output 011: EMI countermeasure circuit period measurement mode 100: IOP output (BD_Read + MOD only) 101: MODFDAC measurement mode 110: MODADAC measurement mode 111: EMI countermeasure circuit spread measurement mode
4	EMIEN	HFM spectrum diffusion circuit enable 0: Disable 1: Enable
3-2	EMIP	HFM spectrum diffusion – modulation frequency 00: 0.01% (350MHz conversion = 35kHz) 01: 0.02% (350MHz conversion = 70kHz) 10: 0.04% (350MHz conversion = 140kHz) 11: 0.08% (350MHz conversion = 280kHz)
1-0	EMIS	HFM spectrum diffusion – diffusion frequency 00: 0.2% (350MHz conversion = 0.7MHz) 01: 0.4% (350MHz conversion = 1.4MHz) 10: 0.8% (350MHz conversion = 2.8MHz) 11: 1.6% (350MHz conversion = 5.6MHz)

Serial Address 7Ch

Bit	Symbol	Bit definition (BD)	Bit definition (DVD/CD)
7	LDCR5	LDD buffer current 0: Small current 1: Large current (fast waveform)	Ringing adjustment (Tr only) 0: Small 1: Large (fast waveform)
6	LDCR4	LDD buffer signal current ratio 0: 1:4 1: 2:4 (fast waveform)	—
5	LDCR3	LDD buffer bias current 0: Small bias current 1: Large bias current (fast waveform)	—
4-3	LDCR2	Snubber 2 (both Tr and Tf) 00: Slow waveform 01: ↓ 10: ↓ 11: Fast waveform	—
2-0	LDCR1	Snubber 1 (Tr only) 000: Slow waveform 001: ↓ 010: ↓ 011: ↓ 100: ↓ 101: ↓ 110: ↓ 111: Fast waveform	Overshoot adjustment (Tr only) 000: Small 001: ↓ 010: ↓ 011: ↓ 100: ↓ 101: ↓ 110: ↓ 111: Large (fast waveform)

Serial Address 7Dh

Bit	Symbol	Bit definition
7	—	—
6	CH5EN	Channel 5 register control 0: OFF 1: ON
5	CH4EN	Channel 4 register control 0: OFF 1: ON
4	CH3EN	Channel 3 register control 0: OFF 1: ON
3	CH2EN	Channel 2 register control 0: OFF 1: ON
2	REN	Read channel register control 0: OFF 1: ON
1	OSCEN	Channel OSC register control 0: OFF 1: ON
0	CH_CONT	Channel control method selection 0: Normal (pin control) 1: Register control mode

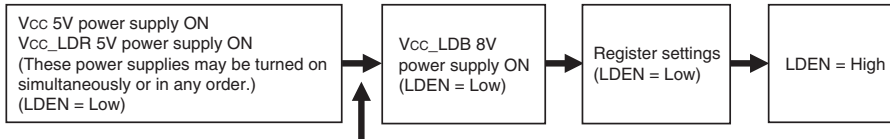
Note) When data is not written to address 78h to 7Dh after power-on, the registers at addresses 78h to 7Dh are undetermined.

Description of Operation

1. Power-on and power-off sequences

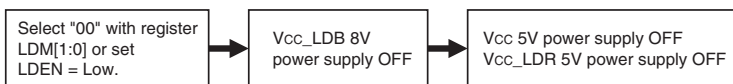
The following sequences are recommended to protect the laser when turning the power on and off.

Power-on sequence



Turn on the Vcc_LDB 8V power supply after the Vcc 5V and Vcc_LDR 5V power supplies have risen to 1V or more. The IC control status is unstable when the Vcc 5V and Vcc_LDR 5V power supplies are less than 1V, so if the Vcc_LDB 8V power supply rises to 7V or more in this condition, current of approximately 10mA may flow to the laser.

Power-off sequence



When LDEN is Low, current does not flow to the laser for any power-off sequence, but the above sequence is recommended.

Note) When the power is forcibly turned off during laser emission, current of the set level or more may flow to the laser.

The conditions for current of the set level or more flowing to the laser are $V_{cc} < 3/5 \times V_{cc_LDR}$ and $V_{cc_LDR} \geq 2V$ (shaded area in the figure below). To avoid problems, Vcc_LDR should be turned off first, or Vcc and Vcc_LDR should be turned off at approximately the same time.

In addition, current of the set level or more does not flow to the laser regardless of the Vcc_LDB 8V power-off order.

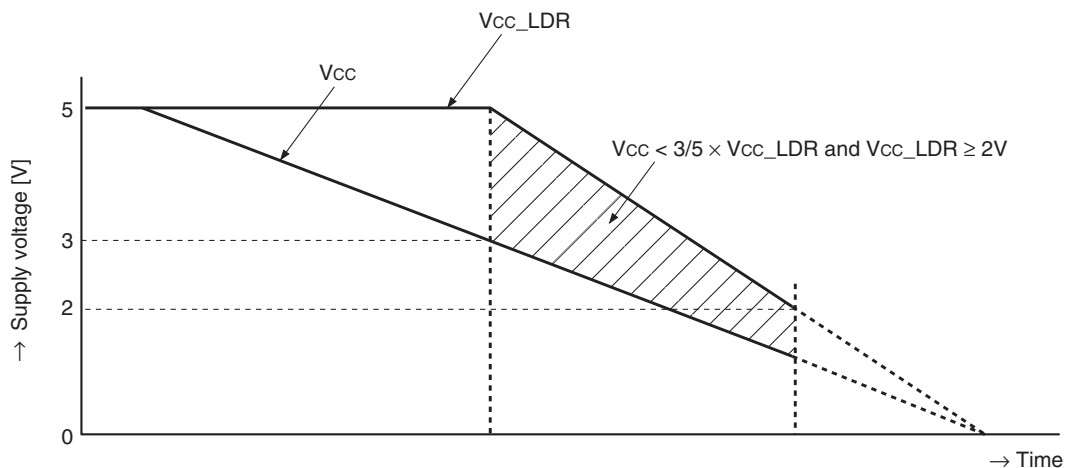


Fig. 1. Vcc and Vcc_LDR Power-off

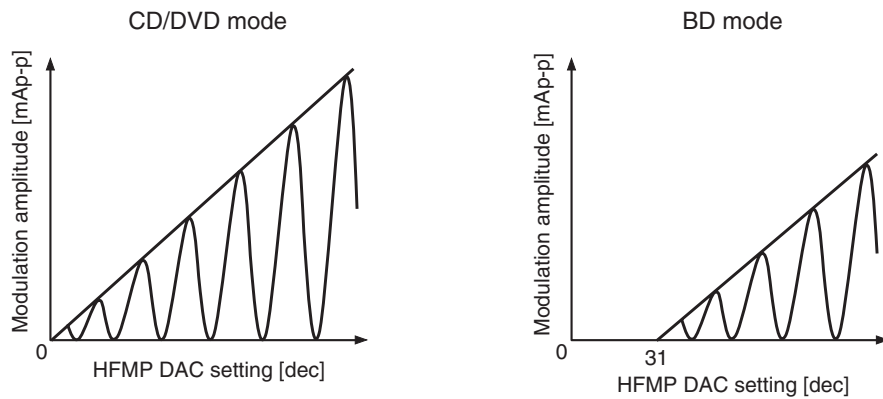
2. LD driving current setting

The currents controlled by the current setting pins IINR, IIN2, IIN3, IIN4 and IIN5 are output from the OUT1, OUT2 and OUTBD pins.
 The output driving currents from the OUT pins can be set independently for IINR, IIN2, IIN3, IIN4 and IIN5 by RDIS, OUTEN and xOUTEN.
 Note that output switching for OUT1 (Pin 19), OUT2 (Pin 21) and OUTBD (Pin 25) is performed by serial address 78h bit[1:0] LDM.

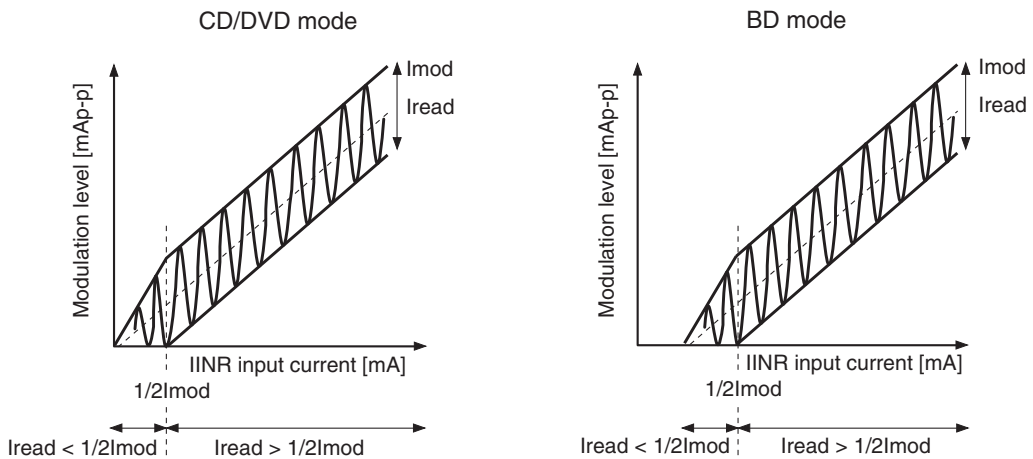
3. Modulator circuit

Output modulation is turned on and off by the OSCEN and xOSCEN pins.
 The modulation frequency can be varied by serial address 7Ah bit[7:0] HFMP, and the modulation amplitude can be varied by serial address 79h bit[7:0] HFMP.

Modulation Amplitude Setting



Modulation Level Adjustment



4. IR pin

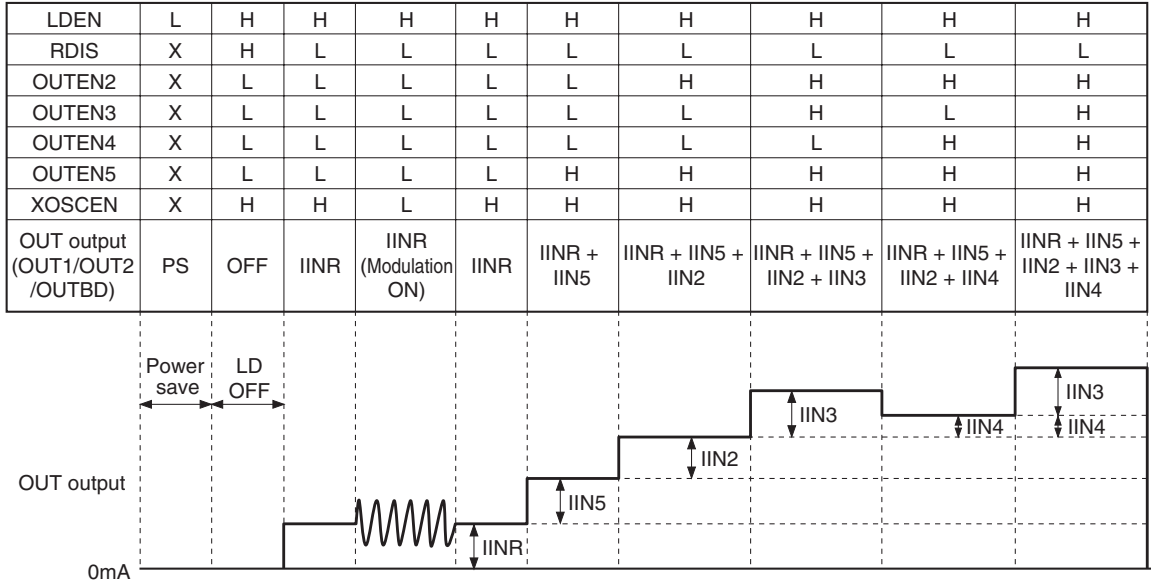
The IR pin external resistor should be fixed to 22kΩ.
 The IR pin aims to reduce variance in the modulation frequency that depends on the internal resistance, and is designed based on fixed resistance of 22kΩ.

Description of Functions

Logic Tables

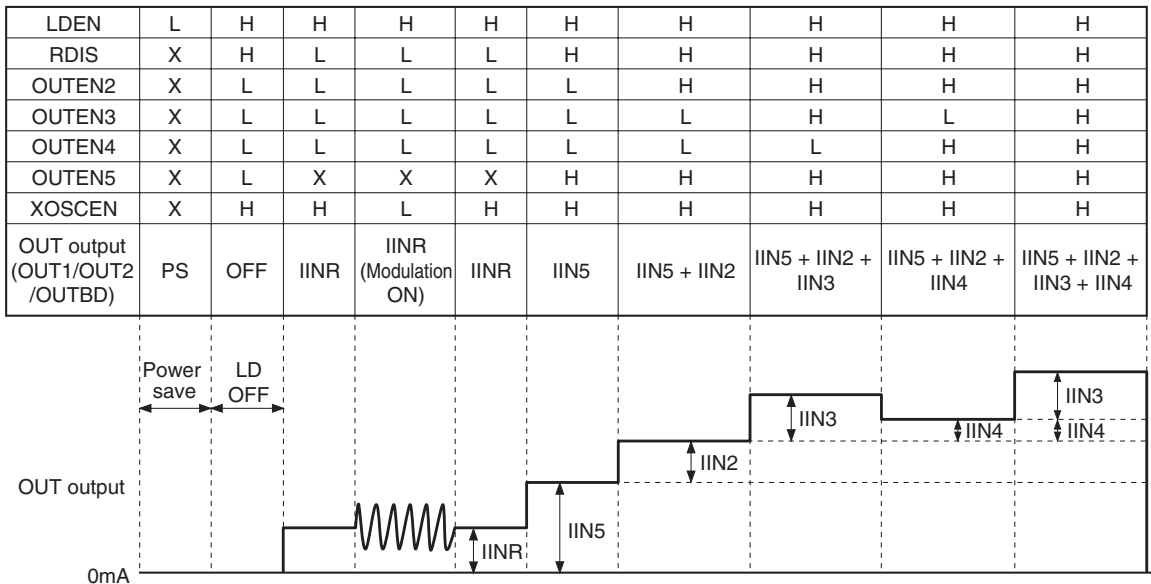
Output control (Differential input)

(X: Don't care)



Output control (Single input)

(X: Don't care)



Note) When serial address 78h bit[5] SEL_CH5 is set High (single input), the IINR channel and the IIN5 channel cannot be added to prevent glitches.

Modulation control

DVD/CD mode

(X: Don't care)

LDEN	L	H	H	H	H	H	H	H	H
RDIS	X	L	L	H	H	H	H	L	H
OUTEN2	X	H	L	H	L	L	L	H	H
OUTEN3	X	H	L	L	H	L	L	L	H
OUTEN4	X	H	L	L	L	H	L	L	L
OUTEN5	X	H	L	L	L	L	H	L	L
XOSCEN	X	H	L	L	L	L	L	L	L
Modulation output (OUT1/OUT2)	PS	Modulation OFF	Modulation ON (IINR)	Modulation ON (IIN2)	Modulation ON (IIN3)	Modulation ON (IIN4)	Modulation ON (IIN5)	Modulation ON (IINR, IIN2)	Modulation ON (IIN2, IIN3)

- Note) 1. Modulation control is independent of the data timing signal.
 2. Modulation is not output from the OUT pin without the input current to IINR.

BD mode

(X: Don't care)

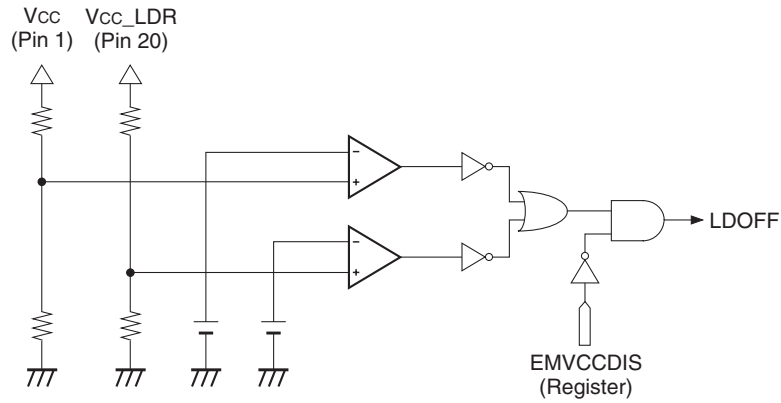
LDEN	L	H	H
RDIS	X	X	L
OUTEN2	X	X	X
OUTEN3	X	X	X
OUTEN4	X	X	X
OUTEN5	X	X	X
XOSCEN	X	H	L
Modulation output (OUTBD)	PS	Modulation OFF	Modulation ON (IINR)

- Note) Modulation is not output from the OUT pin without the input current to IINR.

Power Supply Monitor Circuit

The CXA2765ER has a built-in power supply monitor circuit to ensure safe laser emission. This function monitors the two supply voltages Vcc (Pin 1) and Vcc_LDR (Pin 20). See the “Electrical Characteristics” table for the respective threshold values. When this function detects that either of these power supplies has dropped, it outputs the LDOFF (power save) signal and turns off the laser driving current.

The power supply monitor circuit function can be enabled or disabled by serial address 78h bit[6] EMVCCDIS.

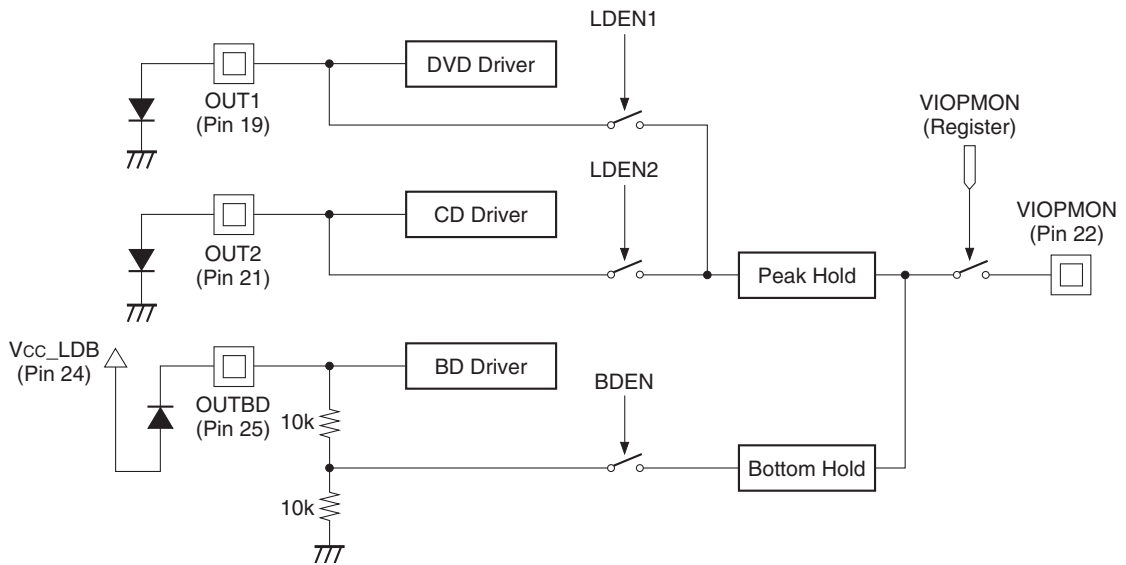


Power Supply Monitor Circuit Block Diagram

VOP Monitor Function

The VOP voltage at the laser end can be monitored.

When serial address 7Bh bit[7:5] are set to “001”, the peak hold voltage (CD/DVD) or the bottom hold voltage (BD) is output from VIOPMON (Pin 22).



VOP Monitor Block Diagram

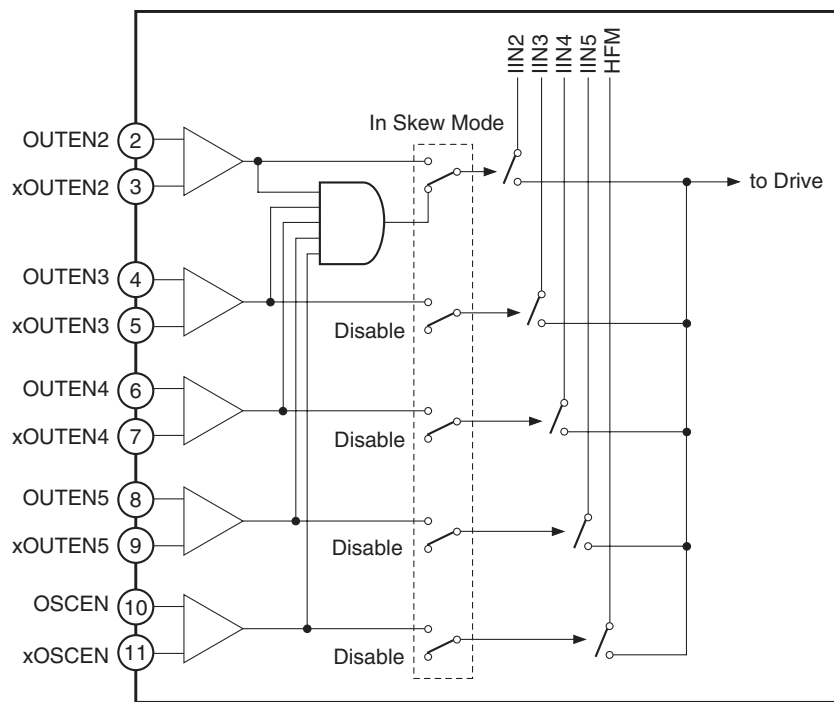
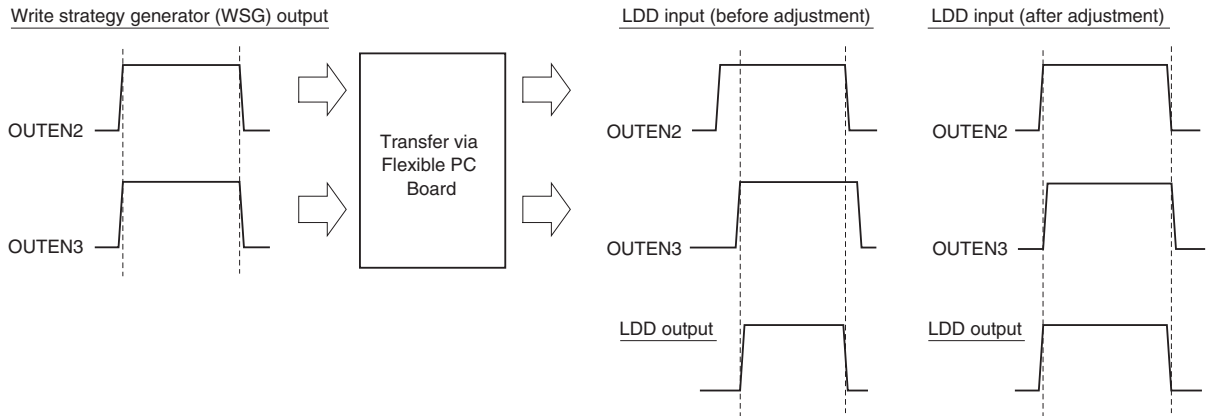
Skew Check Function

Normal mode or skew check mode can be selected by serial address 78h bit[2] SKEW.

The skew check mode is the function that detects the timing offset of recording signals input to the CXA2765ER that occurs between channels due to the effects of the flexible PC board and other factors.

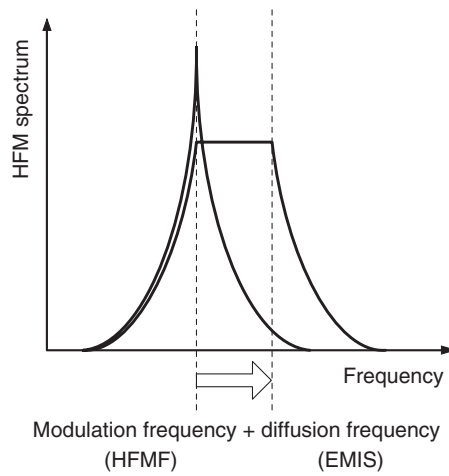
It can detect the timing offset between a total of 5 channels (4 write channels and one OSC channel).

The AND of the recording signals for each channel input to the CXA2765ER is output from the IIN2 channel path. The AND is output, so when the timing is offset between channels, the recording waveform pulse width narrows and the output recording power drops. Adjust the timing of the recording signal for each channel to maximize the output recording power.



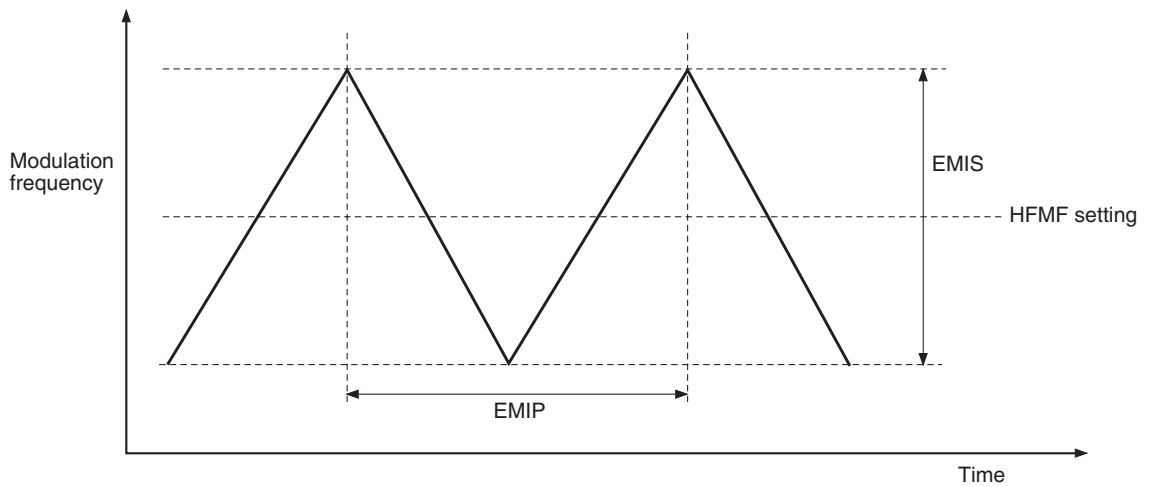
HFM Spectrum Diffusion Function

The HFM spectrum diffusion function is enabled by selecting “1” at Bit4 EMIEN of serial address 7Bh, and the HFM frequency is diffused as shown in the figure below.



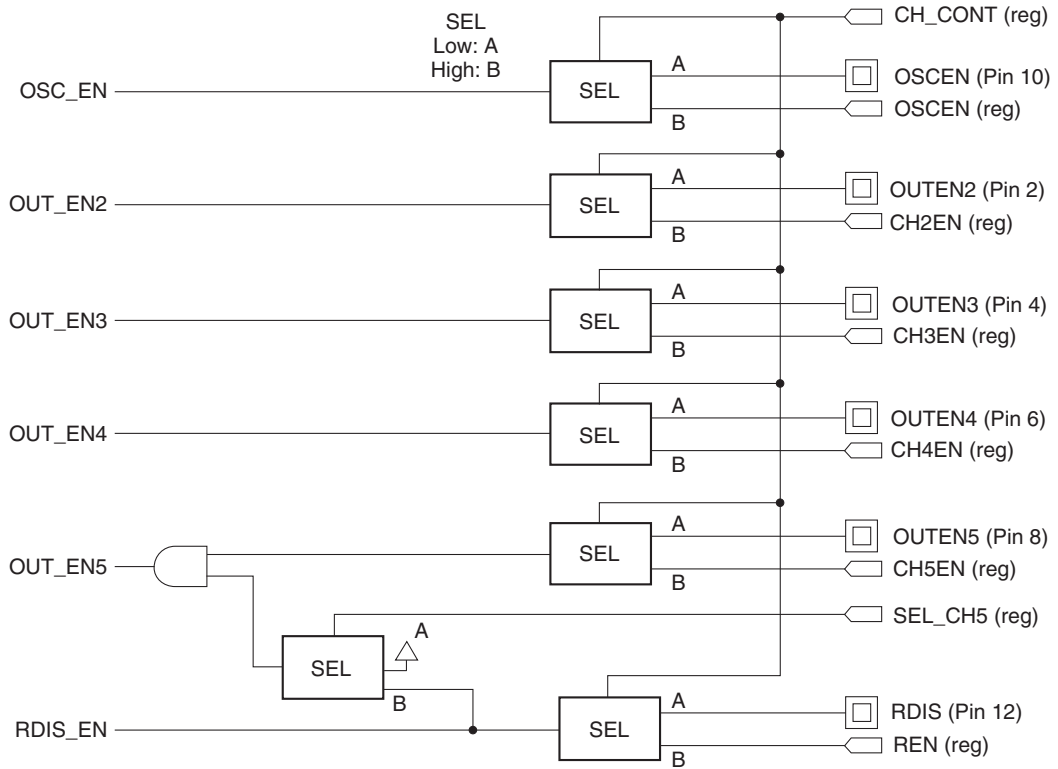
HFM Spectrum Diffusion Frequency Measurement

When serial address 7Bh bit[7:5] are set to “011” or “111”, the HFM spectrum diffusion modulation frequency (EMIP) and diffusion frequency (EMIS) can be measured at VIOPMON (Pin 22).



Channel control

Pin control or bit[6:1] register control can be selected by serial address 7Dh bit[0] CH_CONT.



Read channel and cool channel glitch countermeasures in single input mode

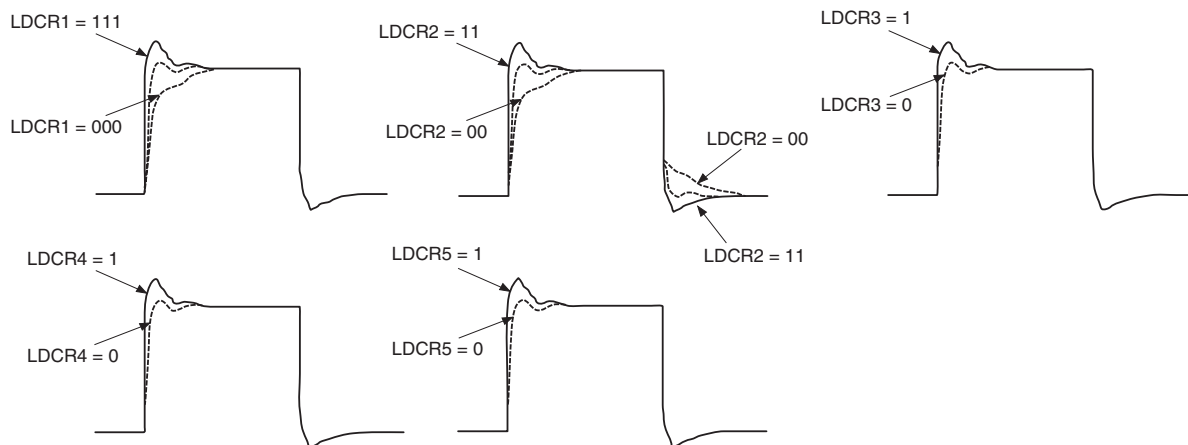
When serial address 78h bit[5] SEL_CH5 is set High (single input), a timing signal which has had glitch countermeasures applied by the read channel and cool channel is output on OUT_EN5. Therefore, the read channel and cool channel cannot be added in single input mode. When set Low (differential input (LVDS)), the cool channel can be added to the read channel to generate the write power.

Changes in the output waveform characteristics by the register settings

The waveform characteristics (rise time (t_r), fall time (t_f), overshoot (OVS+), undershoot (OVS-)) of the output LD driving current change greatly according to the LDD, the LD and the LD load (in the mounted condition) connected to each output pin OUT1 (Pin 19), OUT2 (Pin 21) and OUTBD (Pin 25).

The CXA2765ER can adjust the LDD output waveform characteristics by the register settings. These controls are performed by Serial Address 7Ch. However, in BD mode the current consumption of the 5V block increases as the LDCR5, LDCR4 and LDCR3 settings are increased (faster waveform). In addition, take care in LDCR2 setting because it affects high-frequency modulation amplitude. Modulation amplitude will be larger as LDCR2 setting changes from 00 to 11. In DVD/CD mode the current consumption of the 5 V block increases as the LDCR5 and LDCR1 settings are increased (faster waveform).

<BD waveform adjustment>



<DVD/CD waveform adjustment>



Notes on Operation

- ◆ Make the wiring as short as possible between the output OUT pins (Pins 19, 21 and 25) and the laser diode, and between the V_{CC_LDR} pin and the external decoupling capacitor. As the wiring length increases, the effects of the wiring inductance cause the output waveform overshoot and undershoot to increase.
- ◆ The V_{CC_LDR} pin's external decoupling capacitance ground can be grounded to the GND grounding the load from the OUT pin. This reverses the phase of the drive waveform at the OUT and V_{CC_LDR} and moves in the direction that suppresses overshoots and undershoots.
- ◆ Place the external resistor connected to the IR pin as close to the IC as possible. As the wiring length between the IR pin and the external resistor increases, external disturbance easily enters the reference current generated by the IR pin, and may cause noise to worsen or other problems. In addition, when capacitance is applied to the IR pin, the phase margin with the internal circuits is reduced and oscillation easily occurs.
- ◆ Temperature guarantee
Thermal resistance (θ_{j-a}) when the CXA2765ER is mounted on PWB varies according to the set (PWB) and because it is difficult to predict along with the tendency for higher power for power consumption (P_o), the following points should be considered when using.

Use in a range that the junction temperature (T_j) does not exceed 150°C (T_{jmax}). Also, Use with the thermal resistance (θ_{j-a}) of the PWB mounting lowered so that power consumption (P_o) is below allowable power dissipation (P_D).

It is possible to lower the thermal resistance (θ_{j-a}) when mounted on PWB by widening the GND region with the set PWB or releasing heat to the set chassis, etc.

Find the thermal resistance (θ_{j-a}) when mounted on PWB and power consumption (P_o) using the following method.

$$P_o = (I_{CC} \times V_{CC}) - (I_{OP} \times V_{OP}): \text{DVD/CD mode}$$

$$P_o = (I_{CC} \times V_{CC}) + (I_{OP} \times V_{OP}): \text{BD mode}$$

I_{CC}: IC current consumption when operating (including I_{OP} in DVD/CD mode)

I_{OP}: Output drive current flowed from the OUT pin to the laser diode

V_{OP}: Operating voltage of the laser diode

Thermal resistance (θ_{j-a}) when mounted on PWB

The thermal resistance (θ_{c-a}) is easily obtained by measuring the package surface temperature using a thermo couple or a radiation thermometer.

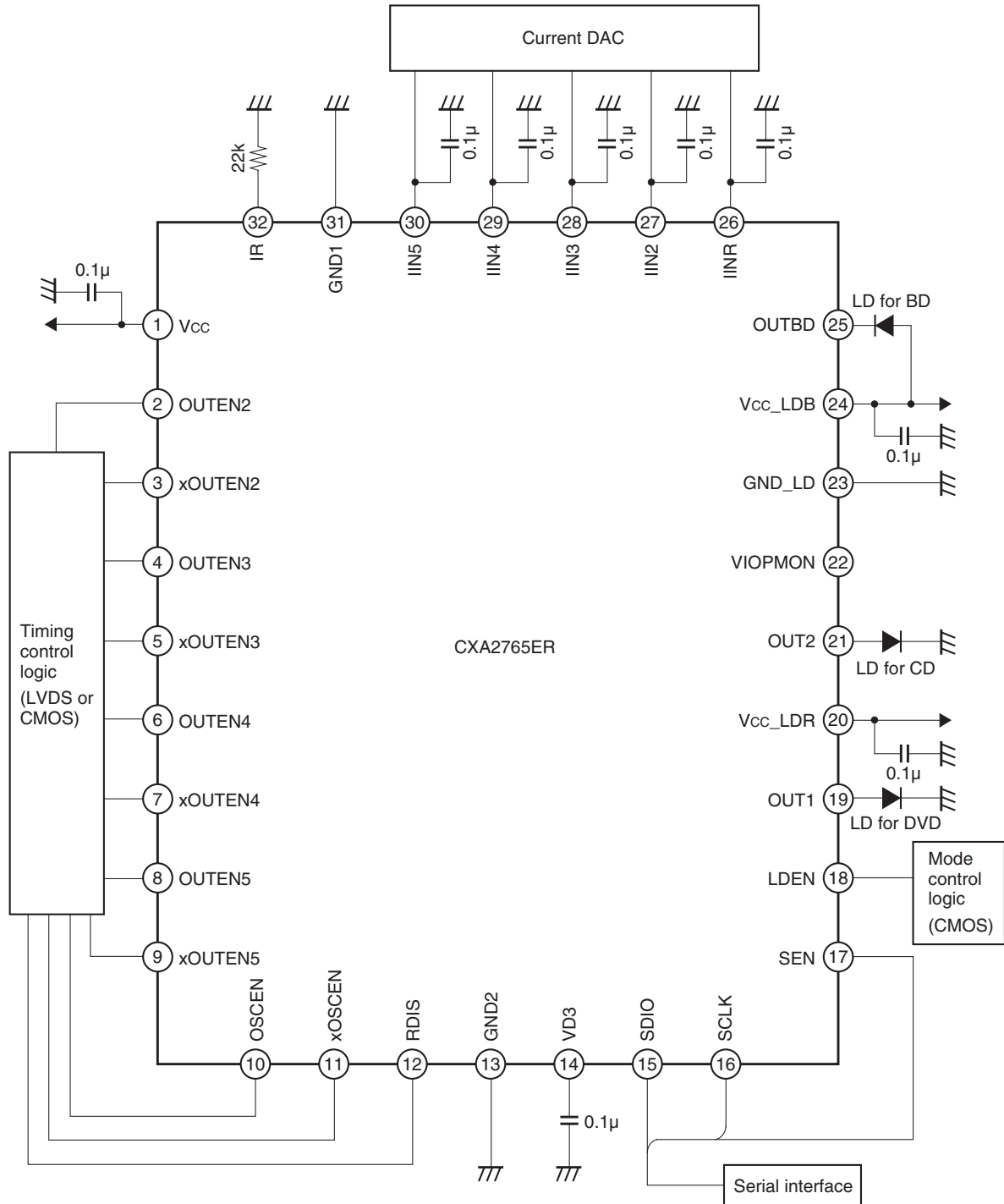
In order to improve the precision of measurement, it is desired to calculate by the following formula.

Δ Package surface temperature when I_{OP} is variable/ ΔP_o

Assume the thermal resistance (θ_{j-c}) to be approximately 2°C/W.

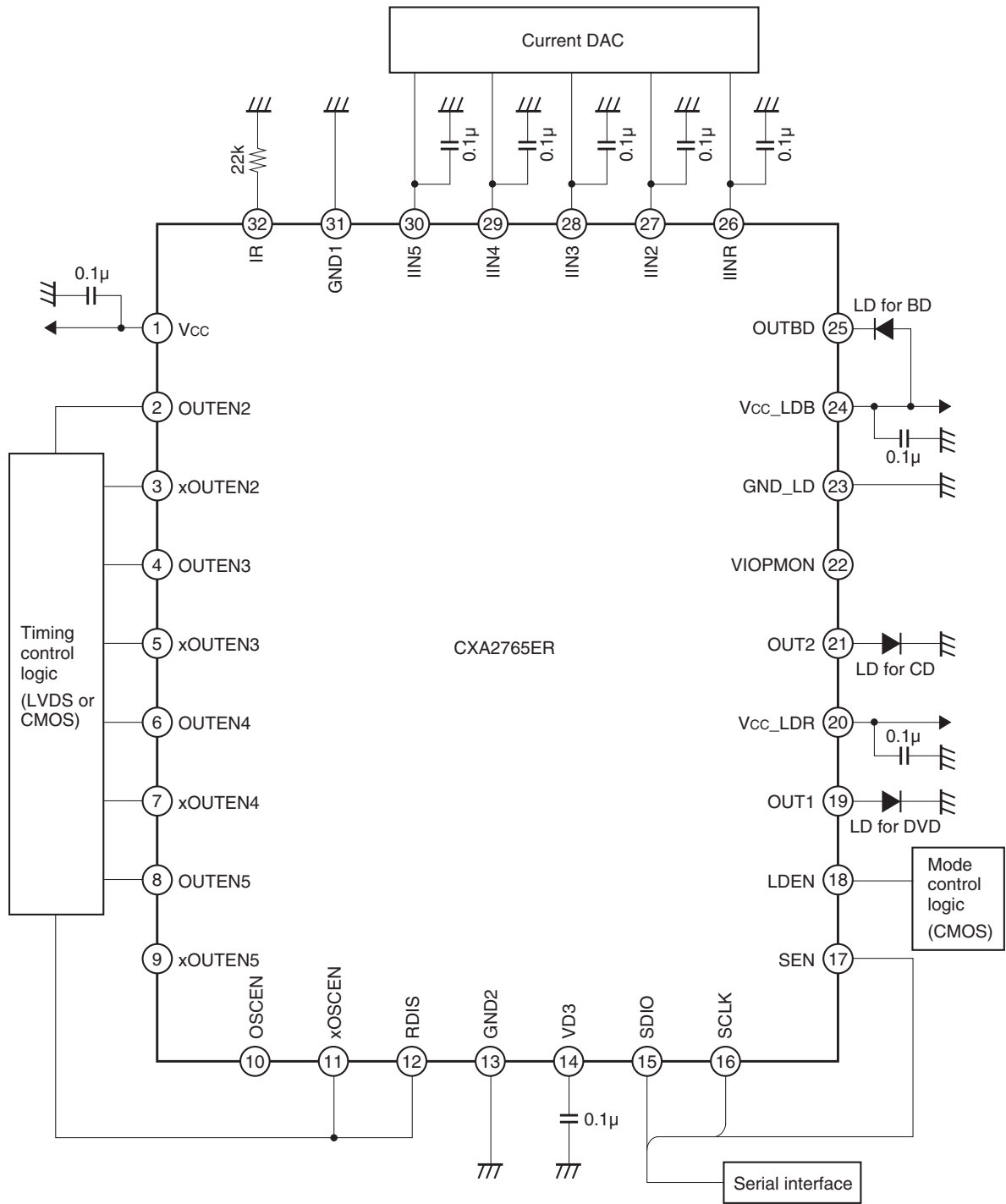
- Thermal resistance (θ_{j-a}) is
 $\theta_{j-a} = \theta_{j-c} + \theta_{c-a}$
- Allowable power dissipation (P_D) $\geq P_o$ [W]
 $P_D = (150^\circ\text{C} - \text{Ambient temperature})/\theta_{j-a}$

Application Circuit 1



Application circuits shown are typical examples illustrating the operation of the devices. Sony cannot assume responsibility for any problems arising out of the use of these circuits or for any infringement of third party patent and other right due to same.

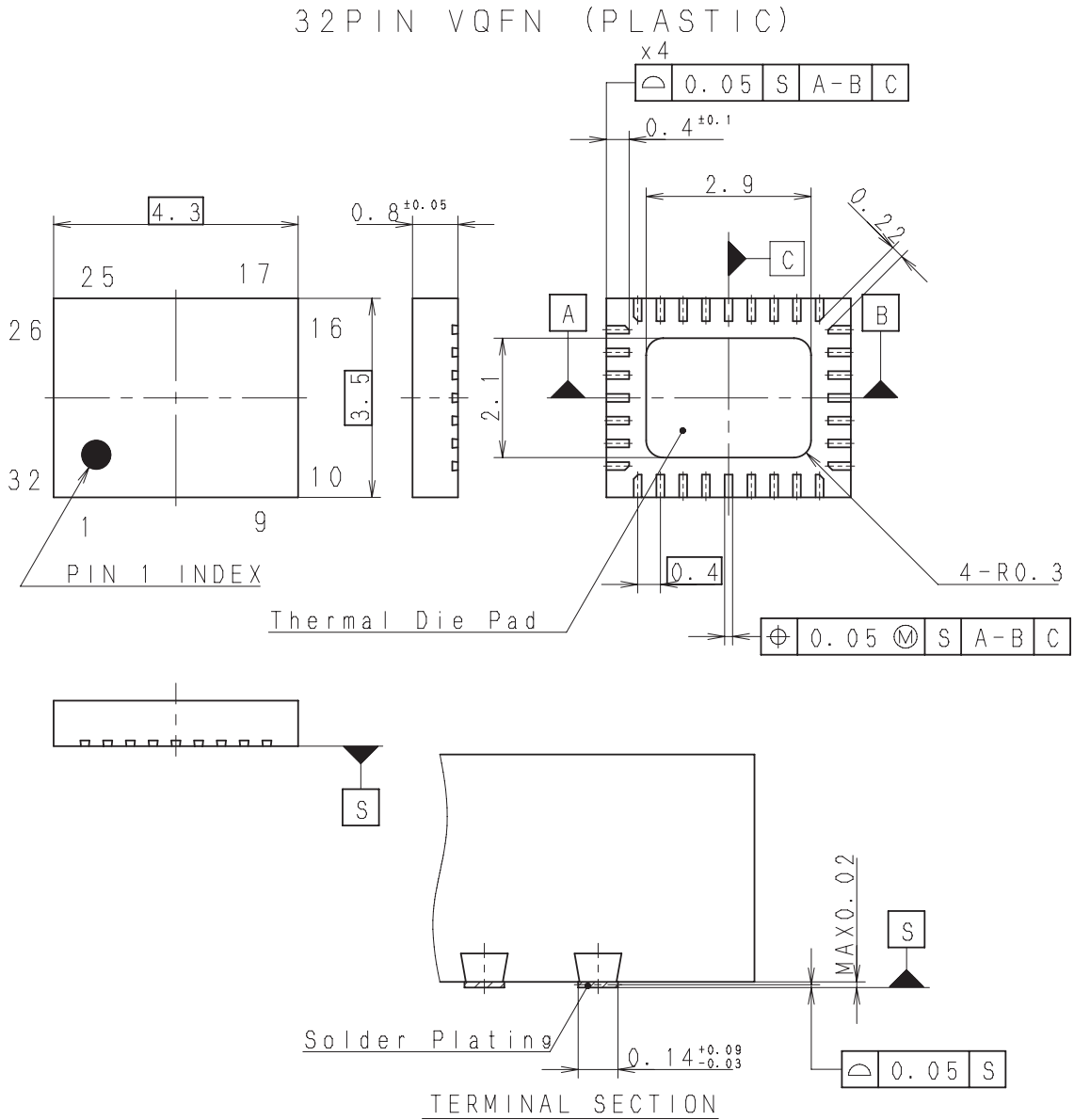
Application Circuit 2



Application circuits shown are typical examples illustrating the operation of the devices. Sony cannot assume responsibility for any problems arising out of the use of these circuits or for any infringement of third party patent and other right due to same.

Package Outline

(Unit: mm)



Note:Cutting burr of lead are 0.05mm MAX.

SONY CODE	VQFN-32P-09
JEITA CODE	_____
JEDEC CODE	_____

AP-4000-32030S

Rev. 0

PACKAGE STRUCTURE

PACKAGE MATERIAL	EPOXY RESIN
LEAD TREATMENT	SOLDER PLATING
LEAD MATERIAL	COPPER ALLOY
PACKAGE MASS	0.04g

LEAD PLATING SPECIFICATIONS

ITEM	SPEC.
LEAD MATERIAL	COPPER ALLOY
SOLDER COMPOSITION	Sn-Bi Bi:1-4wt%
PLATING THICKNESS	5-18μm